

N-Channel Depletion-Mode Vertical DMOS FETs

Features

- ▶ High input impedance
- Low input capacitance
- Fast switching speeds
- Low on resistance
- ► Free from secondary breakdown
- Low input and output leakage

Applications

- Normally-on switches
- Solid state relays
- Converters
- Constant current sources
- Power supply circuits
- Telecom

General Description

The Supertex DN3525 is a low threshold depletion-mode (normally-on) transistor utilizing an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Product marking for TO-243AA:

DN5C*

where * = 2-week alpha date code

Ordering Information

BV _{DSX} /	R _{DS/ON}	l _{nee}	Package Options		
BV _{DGX}	(max)	'DSS (min)	TO-243AA1		
250V	6.0Ω	300mA	DN3525N8		
			DN3525N8-G		

-G indicates package is RoHS compliant ('Green')

Notes: 1Same as SOT-89.



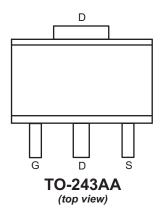


Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSX}
Drain-to-gate voltage	BV _{DGX}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C
Soldering temperature*	300°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Pin Configuration



^{*}Distance of 1.6mm from case for 10 seconds.

Thermal Characteristics

Package	I _D (continuous)¹	I _D (pulsed)	Power Dissipation @T _A = 25°C	Θ _{jc} (°C/W)	Θ _{ja} (°C/W)	l _{DR} 1	l _{DRM}
TO-243AA	360mA	1.0A	1.6W ²	15	78 ²	360mA	1.0A

Notes:

- 1. I_D (continuous) is limited by max rated T_D 2. Mounted on FR4 board, 25mm x 25mm x 1.57mm. Significant P_D increase possible on ceramic substrate.

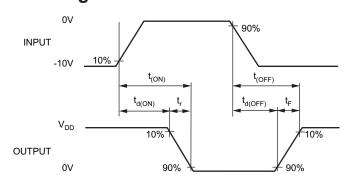
Electrical Characteristics (@25°C unless otherwise specified)

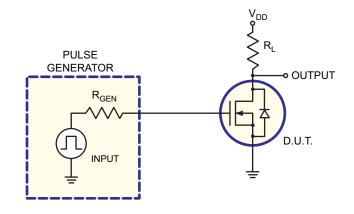
Symbol	Parameter	Min	Тур	Max	Units	Conditions	
BV _{DSX}	Drain-to-source breakdown voltage	250	-	-	V	$V_{GS} = -5.0V, I_{D} = 100 \mu A$	
V _{GS(OFF)}	Gate-to-source OFF voltage	-1.5	-	-3.5	V	$V_{DS} = 15V, I_{D} = 1.0 \text{mA}$	
$\Delta V_{GS(OFF)}$	Change in V _{GS(OFF)} with temperature	-	-	4.5	mV/°C	$V_{DS} = 15V, I_{D} = 1.0mA$	
l _{GSS}	Gate body leakage current	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
		-	-	1.0	μΑ	V_{DS} = Max rating, V_{GS} = -5.0V	
l _{D(OFF)}	rain-to-source leakage current	-	-	1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = -5.0V$, $T_{A} = 125^{\circ}C$	
I _{DSS}	Saturated drain-to-source current	300	-	-	mA	$V_{GS} = 0V, V_{DS} = 15V$	
R _{DS(ON)}	Static drain-to-source ON-state resistance	-	1	6.0	Ω	$V_{GS} = 0V, I_{D} = 200 \text{mA}$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	-	1.1	%/°C	$V_{GS} = 0V, I_D = 200mA$	
G _{FS}	Forward transconductance	225	-	-	mmho	$V_{DS} = 10V, I_{D} = 150mA$	
C _{ISS}	Input capacitance	-	270	350		V _{GS} = -5.0V,	
C _{oss}	Common source output capacitance	-	20	60	pF	$V_{DS} = 25V$,	
C _{RSS}	Reverse transfer capacitance	-	5.0	20		f = 1.0MHz	
t _{d(ON)}	Turn-ON delay time	-	-	20		$V_{DD} = 25V,$ $I_{D} = 150 \text{mA},$ $R_{GEN} = 25\Omega,$ $V_{GS} = 0V \text{ to -10V}$	
t _r	Rise time	-	-	25	no		
t _{d(OFF)}	Turn-OFF delay time	-	-	25	ns		
t _f	Fall time	-	-	40			
V _{SD}	Diode forward voltage drop	-	-	1.8	V	V _{GS} = -5.0V, I _{SD} = 150mA	
t _{rr}	Reverse recovery time	-	800	-	ns	$V_{GS} = -5.0V, I_{SD} = 150mA$	

Notes:

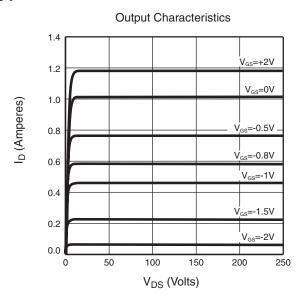
- 1.All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2.All A.C. parameters sample tested.

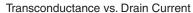
Switching Waveforms and Test Circuit

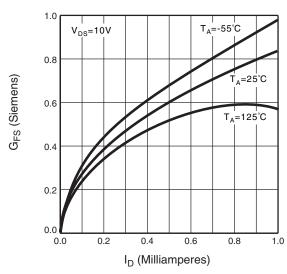




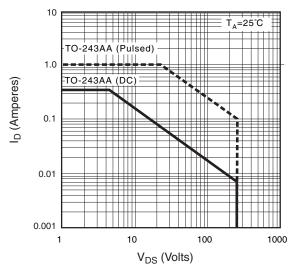
Typical Performance Curves



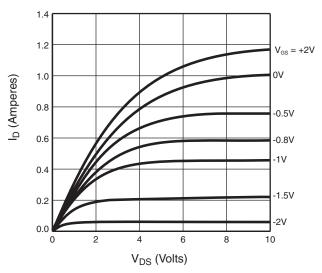




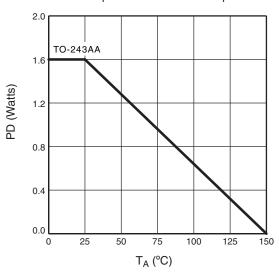
Maximum Rated Safe Operating Area



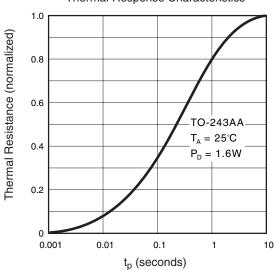
Saturation Characteristics



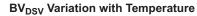
Power Dissipation vs. Ambient Temperature

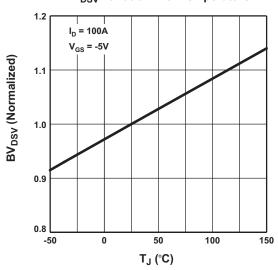


Thermal Response Characteristics

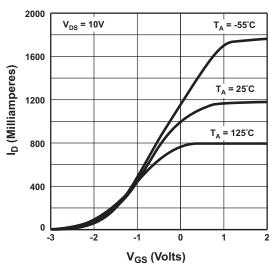


Typical Performance Curves (cont.)

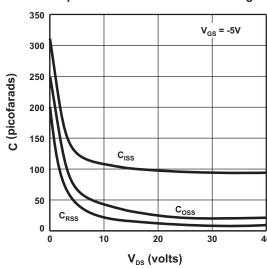




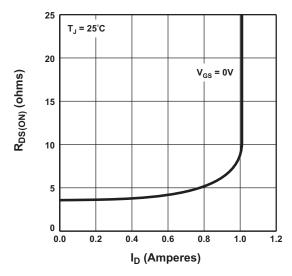
Transfer Characteristics



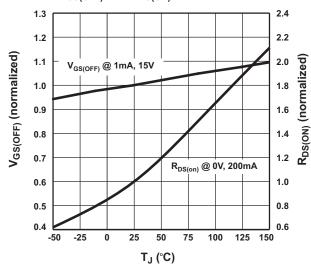
Capacitance vs. Drain Source Voltage



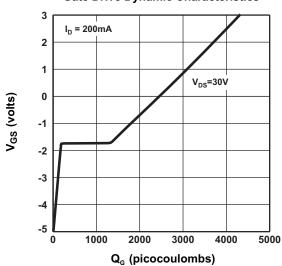
On Resistance vs. Drain Current



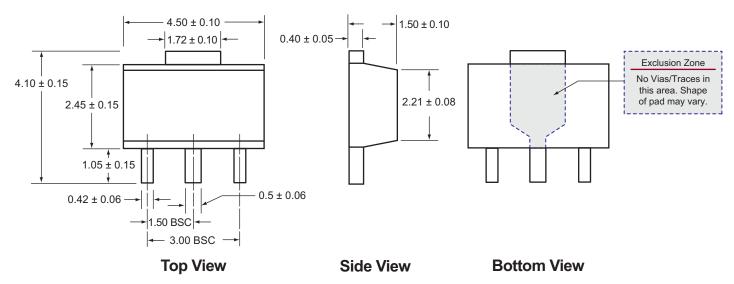
V_{GS(OFF)} and R_{DS(ON)} w/ Temperature



Gate Drive Dynamic Characteristics



3-Lead TO-243AA (SOT-89) Surface Mount Package (N8)



Notes:

All dimensions are in millimeters; all angles in degrees.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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